

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S4	6	(McColloch near2 Ray).in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 06:53
S2	6	(McColloch near3 Laurence near2 Ray).in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 06:53
S1	2	("20050129074").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/12 06:53
S3	12	(McColloch near3 Laurence).in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 07:11
S5	6083	laser and (submount or mount or substrate or wafer) and lid and ((metal or layer or surface or region or film) with (In or Ga or Hg or Sn or Pb or indium or gallium or mercury or tin or lead))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 07:21
S6	8257	laser and (submount or mount or substrate or wafer or base) and lid and ((metal or layer or surface or region or film) with (In or Ga or Hg or Sn or Pb or indium or gallium or mercury or tin or lead))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 07:22
S7	56339	laser and (submount or mount or substrate or wafer or base) and (lid or cover) and ((metal or layer or surface or region or film) near3 (In or Ga or Hg or Sn or Pb or indium or gallium or mercury or tin or lead))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 07:23
S10	16	(laser near3 die) and (submount or mount or substrate or wafer or base) and (lid or cover) and ((metal or layer or surface or region or film) near3 (In or Ga or Hg or Sn or Pb or indium or gallium or mercury or tin or lead)) and (photodetector or (photo near3 detector)) and "372"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 07:24
S8	4685	laser and (submount or mount or substrate or wafer or base) and (lid or cover) and ((metal or layer or surface or region or film) near3 (In or Ga or Hg or Sn or Pb or indium or gallium or mercury or tin or lead)) and (photodetector or (photo near3 detector))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 07:24
S11	57	(laser near3 die) and (submount or mount or substrate or wafer or base) and (lid or cover) and ((metal or layer or surface or region or film) near3 (In or Ga or Hg or Sn or Pb or indium or gallium or mercury or tin or lead)) and (photodetector or (photo near3 detector))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 07:37
S12	90	(laser near3 die) and (submount or mount or substrate or wafer or base) and (lid or cover or housing or packag\$3) and ((metal or layer or surface or region or film) near3 (In or Ga or Hg or Sn or Pb or indium or gallium or mercury or tin or lead)) and (photodetector or (photo near3 detector))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 07:38

S13	19	(laser near3 die) and (submount or mount or substrate or wafer or base) and (lid or cover or housing or packag\$3) and ((metal or layer or surface or region or film) near3 (In or Ga or Hg or Sn or Pb or indium or gallium or mercury or tin or lead)) and ((photodetector near3 die) or (photo near3 detector near3 die))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 07:46
S16	1	S15 AND S14	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 08:11
S19	1	S15 and S17	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 08:12
S18	31	(laser NEAR3 die) and ((metal or layer or surface or region or film) near3 (In or Ga or Hg or Sn or Pb or indium or gallium or mercury or tin or lead)) and ((photodetector) or (photo near3 detector)) and (laser near3 driv\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 08:12
S17	126	(laser NEAR3 die) and ((metal or layer or surface or region or film) near3 (In or Ga or Hg or Sn or Pb or indium or gallium or mercury or tin or lead)) and ((photodetector) or (photo near3 detector))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 08:12
S21	11	(laser near3 die) and (submount\$3 or mount\$3 or substrate or wafer or base) and (lid or cover or housing or packag\$3) and ((metal or layer or surface or region or film) near3 (In or Ga or Hg or Sn or Pb or indium or gallium or mercury or tin or lead)) and ((photodetector near3 die) or (photo near3 detector near3 die)) and (laser near3 driv\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 08:13
S20	1	S15 and S18	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 08:13
S14	19	(laser near3 die) and (submount\$3 or mount\$3 or substrate or wafer or base) and (lid or cover or housing or packag\$3) and ((metal or layer or surface or region or film) near3 (In or Ga or Hg or Sn or Pb or indium or gallium or mercury or tin or lead)) and ((photodetector near3 die) or (photo near3 detector near3 die))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 08:13
S22	5	(laser near3 die) and (submount\$3 or mount\$3 or substrate or wafer or base) and (lid or cover or housing or packag\$3) and ((metal or layer or surface or region or film) near3 (In or Ga or Hg or Sn or Pb or indium or gallium or mercury or tin or lead)) and ((photodetector near3 die) or (photo near3 detector near3 die)) and (laser near3 driv\$3 near3 die)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 08:14
S25	2	(laser near3 die) and (submount\$3 or mount\$3 or substrate or wafer or base) and (lid or cover or housing or packag\$3) and ((metal or layer or surface or region or film) near3 ((cold near3 flow\$3) or creep\$4)) and ((photodetector) or (photo near3 detector)) and (laser near3 driv\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 08:17
S24	2	(laser near3 die) and (submount\$3 or mount\$3 or substrate or wafer or base) and (lid or cover or housing or packag\$3) and ((metal or layer or surface or region or film) near3 ((cold near3 flow\$3) or creep\$4)) and ((photodetector near3 die) or (photo near3 detector near3 die)) and (laser near3 driv\$3 near3 die)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 08:17

S26	2	(laser) and (submount\$3 or mount\$3 or substrate or wafer or base) and (lid or cover or housing or packag\$3) and ((metal or layer or surface or region or film) near3 ((cold near3 flow\$3) or creep\$4)) and ((photodetector) or (photo near3 detector)) and (laser near3 driv\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 08:23
S27	808	(laser) and (submount\$3 or mount\$3 or substrate or wafer or base) and (lid or cover or housing or packag\$3) and ((metal or layer or surface or region or film) near3 ((cold near3 flow\$3) or creep\$4) or cool\$4) and ((photodetector) or (photo near3 detector)) and (laser near3 driv\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 08:24
S29	5	(laser) and (submount\$3 or mount\$3 or substrate or wafer or base) and (lid or cover or housing or packag\$3) and ((metal or layer or surface or region or film) WITH ((cold near3 flow\$3) or creep\$4)) and (thermal\$4 or cool\$4) and ((photodetector) or (photo near3 detector)) and (laser near3 driv\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 08:26
S30	5	(laser) and (submount\$3 or mount\$3 or substrate or wafer or base) and (lid or cover or housing or packag\$3) and ((metal or layer or surface or region or film or medium) WITH ((cold near3 flow\$3) or creep\$4)) and (thermal\$4 or cool\$4) and ((photodetector) or (photo near3 detector)) and (laser near3 driv\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 08:28
S32	626	(laser) and (submount\$3 or mount\$3 or substrate or wafer or base) and (lid or cover or housing or packag\$3) and ((metal or layer or surface or region or film or medium) near4 ((cold near3 flow\$3) or creep\$4)) and (thermal\$4 or cool\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 08:34
S31	931	(laser) and (submount\$3 or mount\$3 or substrate or wafer or base) and (lid or cover or housing or packag\$3) and ((metal or layer or surface or region or film or medium) WITH ((cold near3 flow\$3) or creep\$4)) and (thermal\$4 or cool\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 08:34
S34	5	(laser) and (submount\$3 or mount\$3 or substrate or wafer or base) and (lid or cover or housing or packag\$3) and ((metal or layer or surface or region or film or medium) near4 ((cold near3 flow\$3) or creep\$4)) and (thermal\$4 or cool\$4) and ((photodetector) or (photo near3 detector) or detector or photodiode or (photo near3 diode)) and (laser near3 driv\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 08:36
S35	11	("4661959" "4998256" "5436920").PN. OR ("6219364").URPN.	US-PGPUB; USPAT; USOCR	AND	ON	2006/01/12 08:37
S33	317	(laser) and (submount\$3 or mount\$3 or substrate or wafer or base) and (lid or cover or housing or packag\$3) and ((metal or layer or surface or region or film or medium) near4 ((cold near3 flow\$3) or creep\$4)) and (thermal\$4 or cool\$4) and ((photodetector) or (photo near3 detector) or detector or photodiode or (photo near3 diode))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 08:39
S36	2	(laser) and (submount\$3 or mount\$3 or substrate or wafer or base) and (lid or cover or housing or packag\$3) and ((metal or layer or surface or region or film or medium) near4 ((cold near3 flow\$3) or creep\$4)) and (thermal\$4 or cool\$4) and ((photodetector) or (photo near3 detector) or detector or photodiode or (photo near3 diode)) and "372"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 09:44
S37	5	(laser) and (submount\$3 or mount\$3 or substrate or wafer or base) and (lid or cover or housing or packag\$3) and ((metal or layer or surface or region or film or medium) near4 ((cold near3 flow\$3) or creep\$4)) and (thermal\$4 or cool\$4) and ((photodetector) or (photo near3 detector) or detector or photodiode or (photo near3 diode)) and (laser near3 driv\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 09:45
S38	5	(laser) and (lid or cover or housing or packag\$3) and ((metal or layer or surface or region or film or medium) near4 ((cold near3 flow\$3) or creep\$4)) and (thermal\$4 or cool\$4) and ((photodetector) or (photo near3 detector) or detector or photodiode or (photo near3 diode)) and (laser near3 driv\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 09:46

S39	35	372/34.ccls. and 372/38.02.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 10:03
S40	628	(laser near3 packag\$3) and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 10:09
S41	97	(laser near3 packag\$3) and "257"/\$.ccls. and "372"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 10:13
S42	27	(laser near3 packag\$3) and "257"/\$.ccls. and "372"/\$.ccls. and (laser near3 driv\$4) and ((photodetector) or (photo near3 detector) or detector or photodiode or (photo near3 diode))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 10:23
S45	18	(laser near3 packag\$3) and "257"/\$.ccls. and "372"/\$.ccls. and (laser near3 driv\$4) and ((photodetector) or (photo near3 detector) or detector or photodiode or (photo near3 diode)) and (thermal\$4 or cool\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 10:26
S44	0	(laser near3 packag\$3) and "257"/\$.ccls. and "372"/\$.ccls. and (laser near3 driv\$4) and ((photodetector) or (photo near3 detector) or detector or photodiode or (photo near3 diode)) and ((metal or layer or surface or region or film or medium) near4 ((cold near3 flow\$3) or creep\$4))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 10:26
S46	14	(laser near3 packag\$3) and "257"/\$.ccls. and "372"/\$.ccls. and (laser near3 driv\$4) and ((photodetector) or (photo near3 detector) or detector or photodiode or (photo near3 diode)) and ((metal or layer or surface or region or film or medium) near4 ((cold near3 flow\$3) or creep\$4) or Ga or Hg or Sn or Pb or indium or gallium or mercury or tin or lead) and (thermal\$4 or cool\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 10:27
S43	0	(laser near3 packag\$3) and "257"/\$.ccls. and "372"/\$.ccls. and (laser near3 driv\$4) and ((photodetector) or (photo near3 detector) or detector or photodiode or (photo near3 diode)) and ((metal or layer or surface or region or film or medium) near4 ((cold near3 flow\$3) or creep\$4)) and (thermal\$4 or cool\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 10:27
S47	21	(laser near3 packag\$3) and "257"/\$.ccls. and "372"/\$.ccls. and (laser near3 driv\$4) and ((photodetector) or (photo near3 detector) or detector or photodiode or (photo near3 diode)) and ((metal or layer or surface or region or film or medium) near4 ((cold near3 flow\$3) or creep\$4) or Ga or Hg or Sn or Pb or indium or gallium or mercury or tin or lead)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 10:28
S49	1	(laser near3 die) and (submount\$3 or mount\$3 or substrate or wafer or base) and (lid or cover or housing or packag\$3) and ((metal or layer or surface or region or film or conduct\$3) near3 (Ga or Hg or Sn or Pb or indium or gallium or mercury or tin or lead)) and ((photodetector near3 die) or (photo near3 detector near3 die)) and (laser near3 driv\$3 near3 die)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 10:33
S51	2	(laser near3 packag\$3) and (laser near3 driv\$4) and ((photodetector) or (photo near3 detector) or detector or photodiode or (photo near3 diode)) and ((metal or layer or surface or region or film or medium) near4 ((cold near3 flow\$3) or creep\$4))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 10:39

S48	686	((laser near3 packag\$3) and (laser near3 driv\$4) and ((photodetector) or (photo near3 detector) or detector or photodiode or (photo near3 diode)) and ((metal or layer or surface or region or film or medium or conduct\$3) near4 ((cold near3 flow\$3) or creep\$4) or Ga or Hg or Sn or Pb or indium or gallium or mercury or tin or lead))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 10:39
S52	248	((laser near3 packag\$3) and (laser near3 driv\$4) and ((photodetector) or (photo near3 detector) or detector or photodiode or (photo near3 diode)) and ((metal or layer or surface or region or film or medium or conduct\$3) near4 (Ga or Hg or Sn or Pb or indium or gallium or mercury or tin or lead))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 10:40
S50	1	((laser near3 packag\$3) and (laser near3 driv\$4) and ((photodetector) or (photo near3 detector) or detector or photodiode or (photo near3 diode)) and ((metal or layer or surface or region or film or medium or conduct\$3) near4 ((cold near3 flow\$3) or creep\$4)) and ((metal or layer or surface or region or film or medium or conduct\$3) near4 (Ga or Hg or Sn or Pb or indium or gallium or mercury or tin or lead))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 10:40
S54	97	S53 and thermal\$2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 10:52
S55	65	S53 and (thermal\$2 near3 cool\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 10:53
S57	46	((laser near3 packag\$3) and (laser near3 driv\$4) and ((photodetector) or (photo near3 detector) or detector or photodiode or (photo near3 diode)) and (heat near2 sink) and pad\$4 and (thermal\$2 near3 cool\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 11:25
S58	128	((laser near3 packag\$3) and (laser near3 driv\$4) and ((photodetector) or (photo near3 detector) or detector or photodiode or (photo near3 diode)) and ((metal or layer or surface or (heat near2 sink) or region or film or medium or conduct\$3) near4 (Ga or Hg or Sn or Pb or indium or gallium or mercury or tin or lead)) and pad\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 11:26
S53	127	((laser near3 packag\$3) and (laser near3 driv\$4) and ((photodetector) or (photo near3 detector) or detector or photodiode or (photo near3 diode)) and ((metal or layer or surface or region or film or medium or conduct\$3) near4 (Ga or Hg or Sn or Pb or indium or gallium or mercury or tin or lead)) and pad\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 11:26
S60	1	((laser near3 die) (((metal or layer or surface or region or film or conduct\$4) near3 (Ga or Hg or Sn or Pb or indium or gallium or mercury or tin or lead))) and ((photodetector near3 die) or (photo near3 detector near3 die)) and (laser near3 driv\$3 near3 die) and (heat near3 sink)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 11:36
S59	1	((laser near3 die) and (submount\$3 or mount\$3 or substrate or wafer or base) and (lid or cover or housing or packag\$3) and (((metal or layer or surface or region or film or conduct\$4) near3 (Ga or Hg or Sn or Pb or indium or gallium or mercury or tin or lead))) and ((photodetector near3 die) or (photo near3 detector near3 die)) and (laser near3 driv\$3 near3 die) and (heat near3 sink)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 11:38
S62	8	((laser near3 die) and (((metal or layer or surface or region or film or conduct\$4) near3 (Ga or Hg or Sn or Pb or indium or gallium or mercury or tin or lead)) or (heat near2 sink)) and ((photodetector near3 die) or (photo near3 detector near3 die)) and (laser near3 driv\$3 near3 die)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 11:47

S56	8	(laser near3 die) and (submount\$3 or mount\$3 or substrate or wafer or base) and (lid or cover or housing or packag\$3) and (((metal or layer or surface or region or film or conduct\$4) near3 (Ga or Hg or Sn or Pb or indium or gallium or mercury or tin or lead)) or (heat near2 sink)) and ((photodetector near3 die) or (photo near3 detector near3 die)) and (laser near3 driv\$3 near3 die)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 11:47
S63	29	(laser) and (submount\$3 or mount\$3 or substrate or wafer or base) and (lid or cover or housing or packag\$3) and (((metal or layer or surface or region or film or conduct\$4) near3 (Ga or Hg or Sn or Pb or indium or gallium or mercury or tin or lead))) and ((photodetector) or (photo near3 detector)) and (laser near3 driv\$3) and (heat near3 sink) and (thermal\$2 near3 cool\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 11:52
S61	87	(laser) and (submount\$3 or mount\$3 or substrate or wafer or base) and (lid or cover or housing or packag\$3) and (((metal or layer or surface or region or film or conduct\$4) near3 (Ga or Hg or Sn or Pb or indium or gallium or mercury or tin or lead))) and ((photodetector) or (photo near3 detector)) and (laser near3 driv\$3) and (heat near3 sink)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 12:01
S65	159148	(laser) and (submount\$3 or mount\$3 or substrate or wafer or base) and (lid or cover or housing or packag\$3) and (((metal or layer or surface or region or film or conduct\$4) near3 (Ga or Hg or Sn or Pb or indium or gallium or mercury or tin or lead))) and ((photodetector) or (photo near3 detector)) and (laser near3 driv\$3) and (heat near3 sink) or (cool\$4 near3 (element or device))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 12:03
S67	57	(laser) and (((metal or layer or surface or region or film or conduct\$4) near3 (Ga or Hg or Sn or Pb or indium or gallium or mercury or tin or lead))) and ((photodetector) or (photo near3 detector)) and (laser near3 driv\$3) and (heat near3 sink) and pad\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 12:04
S68	14	(laser) and (submount\$3 or mount\$3 or substrate or wafer or base) and (lid or cover or housing or packag\$3 or cap) and (((metal or layer or surface or region or film or conduct\$4) near3 (Ga or Hg or Sn or Pb or indium or gallium or mercury or tin))) and ((photodetector) or (photo near3 detector)) and (laser near3 driv\$3) and (heat near3 sink) and (thermal\$2 near3 cool\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 12:06
S66	7157	(laser) and (((metal or layer or surface or region or film or conduct\$4) near3 (Ga or Hg or Sn or Pb or indium or gallium or mercury or tin or lead))) and ((photodetector) or (photo near3 detector)) and (laser near3 driv\$3) and (heat near3 sink) or (cool\$4 near2 (element or device)) and pad\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 12:06
S64	29	(laser) and (submount\$3 or mount\$3 or substrate or wafer or base) and (lid or cover or housing or packag\$3 or cap) and (((metal or layer or surface or region or film or conduct\$4) near3 (Ga or Hg or Sn or Pb or indium or gallium or mercury or tin or lead))) and ((photodetector) or (photo near3 detector)) and (laser near3 driv\$3) and (heat near3 sink) and (thermal\$2 near3 cool\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 12:06
S71	14	(laser) and (((metal or layer or surface or region or film or conduct\$4) near3 (Ga or Hg or Sn or Pb or indium or gallium or mercury or tin))) and ((photodetector) or (photo near3 detector)) and (laser near3 driv\$3) and (heat near3 sink) and (thermal\$3 near3 cool\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 12:07
S69	7125	(laser) and (((metal or layer or surface or region or film or conduct\$4) near3 (Ga or Hg or Sn or Pb or indium or gallium or mercury or tin))) and ((photodetector) or (photo near3 detector)) and (laser near3 driv\$3) and (heat near3 sink) or (cool\$4 near2 (element or device)) and pad\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 12:07
S70	12	(laser) and (((metal or layer or surface or region or film or conduct\$4) near3 (Ga or Hg or Sn or Pb or indium or gallium or mercury or tin))) and ((photodetector) or (photo near3 detector)) and (laser near3 driv\$3) and (heat near3 sink) and (thermal\$3 near3 cool\$4) and pad\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 12:08

S28	2	(laser) and (submount\$3 or mount\$3 or substrate or wafer or base) and (lid or cover or housing or packag\$3) and ((metal or layer or surface or region or film) near3 ((cold near3 flow\$3) or creep\$4)) and (thermal\$4 or cool\$4) and ((photodetector) or (photo near3 detector)) and (laser near3 driv\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 13:16
S23	1	(laser near3 die) and (submount\$3 or mount\$3 or substrate or wafer or base) and (lid or cover or housing or packag\$3) and ((metal or layer or surface or region or film) near3 (Ga or Hg or Sn or Pb or indium or gallium or mercury or tin or lead)) and ((photodetector near3 die) or (photo near3 detector near3 die)) and (laser near3 driv\$3 near3 die)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 13:18
S72	1	(laser near3 die) and (lid or cover or housing or packag\$3) and ((metal or layer or surface or region or film) near3 (Ga or Hg or Sn or Pb or indium or gallium or mercury or tin)) and ((photodetector or (photo near3 detector) or diode or photodiode or (photo near2 diode)) near3 die) and (laser near3 driv\$3 near3 die)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 13:19
S74	8	(laser near3 die) and ((photodetector or (photo near3 detector) or diode or photodiode or (photo near2 diode)) near3 die) and (laser near3 driv\$3 near3 die) and (heat near2 sink)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 13:21
S75	42	(laser near3 die) and (photodetector or (photo near3 detector) or diode or photodiode or (photo near2 diode)) and (laser near3 driv\$3) and (heat near2 sink)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 13:34
S73	1	(laser near3 die) and ((metal or layer or surface or region or film) near3 (Ga or Hg or Sn or Pb or indium or gallium or mercury or tin)) and ((photodetector or (photo near3 detector) or diode or photodiode or (photo near2 diode)) near3 die) and (laser near3 driv\$3 near3 die) and (heat near2 sink)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 13:34
S77	1519	(laser) and ((metal or layer or surface or region or film) near3 (Ga or Hg or Sn or Pb or indium or gallium or mercury or tin)) and (cover or housing or lid) and (heat near2 sink)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 13:35
S76	35	(laser near3 die) and (photodetector or (photo near3 detector) or photodiode or (photo near2 diode)) and (laser near3 driv\$3) and (heat near2 sink)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 13:35
S78	27	(laser near2 die) and ((metal or layer or surface or region or film) near3 (Ga or Hg or Sn or Pb or indium or gallium or mercury or tin)) and (cover or housing or lid) and (heat near2 sink)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 13:48
S80	205	372/34.ccls. and 372/36.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 13:56
S15	1512	372/34.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 13:56

S79	28	(laser near2 die) and ((metal or layer or region or film or conduct\$3) near5 (Ga or Hg or Sn or Pb or indium or gallium or mercury or tin)) and (cover or housing or lid) and (heat near2 sink)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 14:00
S81	73	(laser near2 die) and ((metal or layer or region or film or conduct\$3) near5 ((cold near3 flow\$3) or yield\$1 or thermal\$2)) and (cover or housing or lid) and (heat near2 sink)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 14:03
S82	75	(laser near2 die) and ((metal or layer or region or film or conduct\$3) near5 ((cool\$4 near2 flow\$3) or (cool\$4 near2 yield\$1) or (cool\$4 near2 down) or (cool\$4 near2 off) or cold or chill or thermal\$2)) and (cover or housing or lid) and (heat near2 sink)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 14:09
S84	61	(laser near2 die) and ((metal or layer or region or film or conduct\$3) near5 ((cool\$4 near2 flow\$3) or (cool\$4 near2 yield\$1) or (cool\$4 near2 down) or (cool\$4 near2 off) or cold or chill\$3)) and (cover or housing or lid)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 14:10
S85	315	(laser) and ((metal or layer or region or film or conduct\$3) near5 ((cold near2 flow\$3) or ((cold or cool\$4) near2 yield\$1) or (cool\$4 near2 down) or (cool\$4 near2 off) or cold or chill\$3)) and (cover or housing or lid) and (heat near2 sink)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 14:12
S83	5	(laser near2 die) and ((metal or layer or region or film or conduct\$3) near5 ((cool\$4 near2 flow\$3) or (cool\$4 near2 yield\$1) or (cool\$4 near2 down) or (cool\$4 near2 off) or cold or chill\$3)) and (cover or housing or lid) and (heat near2 sink)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 14:14
S86	5	(laser near2 die) and ((metal or layer or region or film or conduct\$3) near5 (((cool\$4 or cold) near2 flow\$3) or ((cool\$4 or cold) near2 yield\$1) or ((cool\$4 or cold) near2 down) or ((cool\$4 or cold) near2 off) or cold or chill\$3)) and (cover or housing or lid) and (heat near2 sink)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 14:17
S9	322	laser and (submount or mount or substrate or wafer or base) and (lid or cover) and ((metal or layer or surface or region or film) near3 (In or Ga or Hg or Sn or Pb or indium or gallium or mercury or tin or lead)) and (photodetector or (photo near3 detector)) and "372"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 14:18
S88	375	S87 and (submount or mount or substrate or wafer or base)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 14:26
S87	416	(laser) and ((metal or layer or region or film or conduct\$3) near5 (((cool\$4 or cold) near2 flow\$3) or ((cool\$4 or cold) near2 yield\$1) or ((cool\$4 or cold) near2 down) or ((cool\$4 or cold) near2 off) or cold or chill\$3)) and (cover or housing or lid) and (heat near2 sink)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 14:44
S89	21	(laser near3 packag\$3) and ((metal or layer or region or film or conduct\$3) near5 (((cool\$4 or cold) near2 flow\$3) or ((cool\$4 or cold) near2 yield\$1) or ((cool\$4 or cold) near2 down) or ((cool\$4 or cold) near2 off) or cold or chill\$3)) and (cover or housing or lid) and (heat near2 sink) and (submount or mount or substrate or wafer or base)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 14:46

S90	27	(laser near3 (housing or packag\$3)) and ((metal or layer or region or film or conduct\$3) near5 (((cool\$4 or cold) near2 flow\$3) or ((cool\$4 or cold) near2 yield\$1) or ((cool\$4 or cold) near2 down) or ((cool\$4 or cold) near2 off) or cold or chill\$3)) and (cover or housing or lid) and (heat near2 sink) and (submount or mount or substrate or wafer or base)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 14:50
S91	29	(laser near3 (housing or packag\$3)) and ((metal or layer or region or film or conduct\$3) near5 (((cool\$4 or cold) near2 flow\$3) or ((cool\$4 or cold) near2 yield\$1) or ((cool\$4 or cold) near2 down) or ((cool\$4 or cold) near2 off) or cold or chill\$3)) and (heat near2 sink) and (submount or mount or substrate or wafer or base)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 14:51
S93	98	((("5965946") or ("6162651") or ("6954034") or ("5874011") or ("5973396") or ("5764485") or ("5857049") or ("6168969") or ("6139674") or ("4927992") or ("4945391") or ("5264392") or ("5481082") or ("5749041") or ("4523802") or ("4617723") or ("4911512") or ("4941067") or ("4997253") or ("5018005") or ("5177753") or ("5189781") or ("5226052") or ("5245620") or ("5305344") or ("5309460") or ("5343176") or ("5479029") or ("5544184") or ("5557116") or ("5578227") or ("5612576") or ("5622815") or ("5626278") or ("5694048") or ("5763002") or ("5770238") or ("5774616") or ("5835518") or ("5859942") or ("5867303") or ("5872360") or ("5898718") or ("5903050") or ("5960259") or ("6025213") or ("6037565") or ("6072179") or ("6229097") or ("6244121).pn.") or ("6277656") or ("6277659") or ("6281106") or ("6298075") or ("6303396") or ("6350624") or ("6379777") or ("6649832") or ("6746889") or ("6752308") or ("6823582") or ("6858871") or ("6895029") or ("5334306") or ("4482197") or ("4502745") or ("4503609") or ("4764800") or ("5882773") or ("5896642") or ("6054767") or ("6138544") or ("4436557") or ("5019552") or ("5359687") or ("5640667") or ("5715063") or ("6046426") or ("6143401") or ("4779282") or ("4914669") or ("5012316") or ("5255431") or ("5264912") or ("5351258") or ("5365409") or ("5382457") or ("5461600") or ("5523608") or ("5563702") or ("5572598") or ("5598387") or ("5632204") or ("5653019") or ("5725989") or ("5728994") or ("5733711") or ("5737072") or ("5756175") or ("5770721).pn.")). PN.	USPAT	OR	OFF	2006/01/12 15:25
S92	2	S91 not S90	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/12 15:25
S95	3	(laser near3 die) and (cover or lid) and (metal or (heat near2 (sink or dissipat\$3)))	USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/17 13:50
S94	966	(laser near3 die) and (cover or lid) and (metal or (heat near2 (sink or dissipat\$3)))	US-PGPUB; USPAT	AND	ON	2006/01/17 13:51
S96	526	(laser near3 die) and (cover or lid) and (metal or (heat near2 (sink or dissipat\$3)))	USPAT	AND	ON	2006/01/17 13:52
S99	0	(laser near3 die) and (cover or lid) and ((metal near2 (flow\$3)) or (heat near2 (sink or dissipat\$3)))	USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/17 13:53
S98	122	(laser near3 die) and (cover or lid) and ((metal near2 (flow\$3)) or (heat near2 (sink or dissipat\$3)))	US-PGPUB	AND	ON	2006/01/17 13:53
S97	109	(laser near3 die) and (cover or lid) and ((metal near2 (flow\$3)) or (heat near2 (sink or dissipat\$3)))	USPAT	AND	ON	2006/01/17 13:56
S10 0	20	(laser near3 die) and ((cover\$3 near2 mov\$4) or lid) and ((metal near2 (flow\$3)) or (heat near2 (sink or dissipat\$3)))	USPAT	AND	ON	2006/01/17 15:06
S10 3	0	(laser near1 die) and ((cover\$3 near2 mov\$4) or lid) and ((metal near2 (flow\$3 or creep\$3)) or heatsink or (heat near2 (sink or dissipat\$3))) and "372"/\$.ccls.	USPAT	AND	ON	2006/01/17 15:08
S10 2	26	(laser near3 die) and 372/36.ccls.	USPAT	AND	ON	2006/01/17 15:08
S10 5	72	S97 not S104	US-PGPUB; USPAT	AND	ON	2006/01/17 15:12

S10 8	1	(laser near1 die) and (cover\$3 or frame or lid or housing) and ((metal near2 (flow\$3 or creep\$3 or heat)) or heatsink or (heat near2 (sink or dissipat\$3 or conduct\$3)))	USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/17 15:13
S10 7	51	(laser near1 die) and (cover\$3 or frame or lid or housing) and ((metal near2 (flow\$3 or creep\$3 or heat)) or heatsink or (heat near2 (sink or dissipat\$3 or conduct\$3)))	US-PGPUB	AND	ON	2006/01/17 15:13
S10 4	60	(laser near1 die) and (cover\$3 or frame or lid or housing) and ((metal near2 (flow\$3 or creep\$3)) or heatsink or (heat near2 (sink or dissipat\$3)))	USPAT	AND	ON	2006/01/17 15:13
S10 1	6	(laser near3 die) and 372/34.ccls.	USPAT	AND	ON	2006/01/17 15:16
S10 9	8	(laser near3 die) and 372/34.ccls.	US-PGPUB	AND	ON	2006/01/17 15:17
S11 0	11	S106 and "372"/\$.ccls.	USPAT	AND	ON	2006/01/17 15:25
S11 1	30	S106 and ("372"/\$.ccls. or "257"/\$.ccls. or "4385"/\$.ccls.)	USPAT	AND	ON	2006/01/17 15:26
S10 6	74	(laser near1 die) and (cover\$3 or frame or lid or housing) and ((metal near2 (flow\$3 or creep\$3 or heat)) or heatsink or (heat near2 (sink or dissipat\$3 or conduct\$3)))	USPAT	AND	ON	2006/01/17 15:27
S11 5	1571	(laser) and (cover\$3 or frame or lid or housing) and ((metal near2 (flow\$3 or creep\$3 or heat)) or heatsink or (heat near2 (sink or dissipat\$3 or conduct\$3))) and "438"/\$.ccls.	USPAT	AND	ON	2006/01/17 15:28
S11 4	3474	(laser) and (cover\$3 or frame or lid or housing) and ((metal near2 (flow\$3 or creep\$3 or heat)) or heatsink or (heat near2 (sink or dissipat\$3 or conduct\$3))) and "257"/\$.ccls.	USPAT	AND	ON	2006/01/17 15:28
S11 6	1	("20040164402").PN.	US-PGPUB	OR	OFF	2006/01/17 15:30
S11 3	1497	(laser) and (cover\$3 or frame or lid or housing) and ((metal near2 (flow\$3 or creep\$3 or heat)) or heatsink or (heat near2 (sink or dissipat\$3 or conduct\$3))) and "372"/.ccls.	USPAT	AND	ON	2006/01/17 15:30
S11 2	16449	(laser) and (cover\$3 or frame or lid or housing) and ((metal near2 (flow\$3 or creep\$3 or heat)) or heatsink or (heat near2 (sink or dissipat\$3 or conduct\$3)))	USPAT	AND	ON	2006/01/17 15:33
S11 8	13	(Yoshimura near2 Hideaki).in.	USPAT	AND	ON	2006/01/17 15:34
S11 7	167	(laser near2 die) and (cover\$3 or frame or lid or housing) and ((metal near2 (flow\$3 or creep\$3 or heat)) or heatsink or (heat near2 (sink or dissipat\$3 or conduct\$3)))	USPAT	AND	ON	2006/01/17 15:34
S12 0	0	("2003-044335").PN.	JPO	OR	OFF	2006/01/17 15:47
S12 2	0	((("20010028110") or ("20000031918") or ("5,527,604") or ("5763950") or ("5637925") or ("6127724"))).PN.	JPO	OR	OFF	2006/01/17 15:49
S12 1	1	("2003044335").PN.	JPO	OR	OFF	2006/01/17 15:49
S12 3	5	((("20010028110") or ("20000031918") or ("5,527,604") or ("5763950") or ("5637925") or ("6127724"))).PN.	US-PGPUB; USPAT	OR	OFF	2006/01/17 15:50
S12 4	1	("2004253703").PN.	JPO	OR	OFF	2006/01/17 16:25
S12 7	260	372/36.ccls. and (laser near3 packag\$3)	US-PGPUB; USPAT	AND	ON	2006/01/17 16:26
S12 6	920	372/36.ccls.	US-PGPUB; USPAT	AND	ON	2006/01/17 16:26
S12 5	66	372/36.ccls. and LID	US-PGPUB; USPAT	AND	ON	2006/01/17 16:40
S12 9	4	S125 not S128	US-PGPUB; USPAT	AND	ON	2006/01/17 16:41
S13 0	381	372/36.ccls. and (LID or packag\$3) and laser and (metal or heatsink or (heat near2 (sink or conduct\$4 or dissipat\$3)))	US-PGPUB; USPAT	AND	ON	2006/01/17 16:43
S12 8	62	372/36.ccls. and LID and laser and (metal or heatsink or (heat near2 (sink or conduct\$4 or dissipat\$3)))	US-PGPUB; USPAT	AND	ON	2006/01/17 16:43
S13 1	319	S130 not S125	US-PGPUB; USPAT	AND	ON	2006/01/18 08:06

S13 2	13	("3867003" "4091408" "4566027" "5454002" "5544269" "5578869" "5616886" "5834842" "5913108" "6256200" "6299056" "6306680" "6307871").PN. OR ("6791181").URPN.	US-PGPUB; USPAT; USOCR	AND	ON	2006/01/18 10:49
S11 9	24	(Yoshimura near2 Hideaki).in.	US-PGPUB; USPAT	AND	ON	2006/01/18 14:15
S13 3	3090	257/717,718,712,719.ccls.	US-PGPUB; USPAT	AND	ON	2006/01/18 14:16
S13 7	37	S134 and lid and laser	US-PGPUB; USPAT	AND	ON	2006/01/18 14:17
S13 6	206	S134 and lid	US-PGPUB; USPAT	AND	ON	2006/01/18 14:17
S13 5	244	S134 and laser	US-PGPUB; USPAT	AND	ON	2006/01/18 14:17
S13 4	2069	S133 and (heatsink or (heat near2 sink))	US-PGPUB; USPAT	AND	ON	2006/01/18 14:19
S13 9	3	S133 and (heatsink or (heat near2 sink)) and lid and (laser or chip) AND (photodiode or (photo near2 diode))	US-PGPUB; USPAT	AND	ON	2006/01/18 14:29
S14 1	61	((semiconductor near3 chip) same (laser near2 (dye or die)))	US-PGPUB; USPAT	AND	ON	2006/01/18 14:57
S14 2	32	S141 not S140	US-PGPUB; USPAT	AND	ON	2006/01/18 15:00
S14 0	29	((semiconductor near3 chip) with (laser near2 (dye or die)))	US-PGPUB; USPAT	AND	ON	2006/01/18 15:09
S14 4	2	((("6,515,360") or ("6,369,380")).PN.	US-PGPUB; USPAT	OR	OFF	2006/01/18 15:14
S14 3	10	((("20030183909") or ("6,654,248") or ("6,603,183") or ("6,282,096") or ("5,796,582") or ("20020185748") or ("6,407,461") or ("6,392,890") or ("6,278,182") or ("4,801,998")).PN.	US-PGPUB; USPAT	OR	OFF	2006/01/18 15:14
S14 5	4	S133 and (heatsink or (heat near2 sink)) and lid and (laser or chip) and lens	US-PGPUB; USPAT	AND	ON	2006/01/18 15:41
S14 7	135	S146 and pin\$1	US-PGPUB; USPAT	AND	ON	2006/01/18 15:42
S14 9	212	(heatsink or (heat near2 sink)) and laser and (lens with (substrate or submount or mount)) and pin\$1	USPAT	AND	ON	2006/01/18 15:51
S14 8	435	(heatsink or (heat near2 sink)) and laser and (lens with (substrate or submount or mount)) and pin\$1	US-PGPUB; USPAT	AND	ON	2006/01/18 15:51
S14 6	163	(heatsink or (heat near2 sink)) and lid and (laser or chip) and (lens with (substrate or submount or mount))	US-PGPUB; USPAT	AND	ON	2006/01/18 15:51
S15 0	13	(heatsink or (heat near2 sink)) and laser and (lens with (substrate or submount or mount)) and pin\$1 and "372"/\$.ccls.	USPAT	AND	ON	2006/01/18 15:53
S15 3	48	S151 not S152	US-PGPUB; USPAT	AND	ON	2006/01/18 16:16
S15 1	114	(laser near2 packag\$3) and (lens with (substrate or submount or mount)) and pin\$1	USPAT	AND	ON	2006/01/18 16:16
S15 2	78	(laser near2 packag\$3) and (lens with (base or substrate or wafer or mount or submount)) and (pin\$1 with (base or substrate or wafer or mount or submount))	USPAT	AND	ON	2006/01/18 16:17
S15 4	89	(laser near2 packag\$3) and (lens with (base or substrate or wafer or mount or submount)) and (pin\$1 with (base or substrate or wafer or mount or submount))	US-PGPUB; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/18 16:22
S15 5	3093	257/717,718,712,719.ccls.	US-PGPUB; USPAT	AND	ON	2006/01/19 06:10
S13 8	164	S133 and (heatsink or (heat near2 sink)) and lid and (laser or chip)	US-PGPUB; USPAT	AND	ON	2006/01/19 06:10
S15 8	16	((semiconductor near3 chip) same (laser near2 (dye or die)))	USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/19 06:20
S15 6	3	S155 and (heatsink or (heat near2 sink)) and lid and (photodiode or (photo near2 diode))	US-PGPUB; USPAT	AND	ON	2006/01/19 06:20

S15 7	61	((semiconductor near3 chip) same (laser near2 (dye or die)))	US-PGPUB; USPAT	AND	ON	2006/01/19 06:22
S16 2	76	S161 not S159	US-PGPUB; USPAT	AND	ON	2006/01/19 06:24
S16 1	95	((chip) same (laser near1 (dye or die)))	US-PGPUB; USPAT	AND	ON	2006/01/19 06:24
S16 0	33	((chip) with (laser near1 (dye or die)))	US-PGPUB; USPAT	AND	ON	2006/01/19 06:24
S15 9	19	((semiconductor near3 chip) same (laser near1 (dye or die)))	US-PGPUB; USPAT	AND	ON	2006/01/19 06:27
S16 3	199	((semiconductor near3 chip) and (laser near1 (dye or die)))	US-PGPUB; USPAT	AND	ON	2006/01/19 06:31
S16 4	180	S163 not S157	US-PGPUB; USPAT	AND	ON	2006/01/19 06:56
S16 5	20	S164 and (laser near2 (packag\$3 or housing))	US-PGPUB; USPAT	AND	ON	2006/01/19 06:57
S16 6	368	((TIM or (thermal near2 interface near2 material)) with (Indium or galium or mercury or tin or Ga or Hg or Sn or Pb))	US-PGPUB; USPAT	AND	ON	2006/01/19 07:37
S16 7	183	((TIM or (thermal near2 interface near2 material)) near4 (Indium or galium or mercury or tin or Ga or Hg or Sn or Pb))	US-PGPUB; USPAT	AND	ON	2006/01/19 07:38
S16 8	25	((((thermal near2 interface near2 material)) near4 (Indium or galium or mercury or tin or Ga or Hg or Sn or Pb))	US-PGPUB; USPAT	AND	ON	2006/01/19 07:49
S16 9	3	((((thermal near2 interface near2 material)) near4 (Indium or galium or mercury or tin or Ga or Hg or Sn or Pb)) and laser	US-PGPUB; USPAT	AND	ON	2006/01/19 07:57
S17 0	11	((((thermal near2 interface near2 material)) WITH (Indium or galium or mercury or tin or Ga or Hg or Sn or Pb)) and laser	US-PGPUB; USPAT	AND	ON	2006/01/19 08:23
S17 1	11	((((thermal near2 interface near2 material)) WITH (Indium or galium or mercury or tin or Ga or Hg or Sn or Pb)) and laser and (semiconductor (device or laser or chip))	US-PGPUB; USPAT	AND	ON	2006/01/19 08:24